



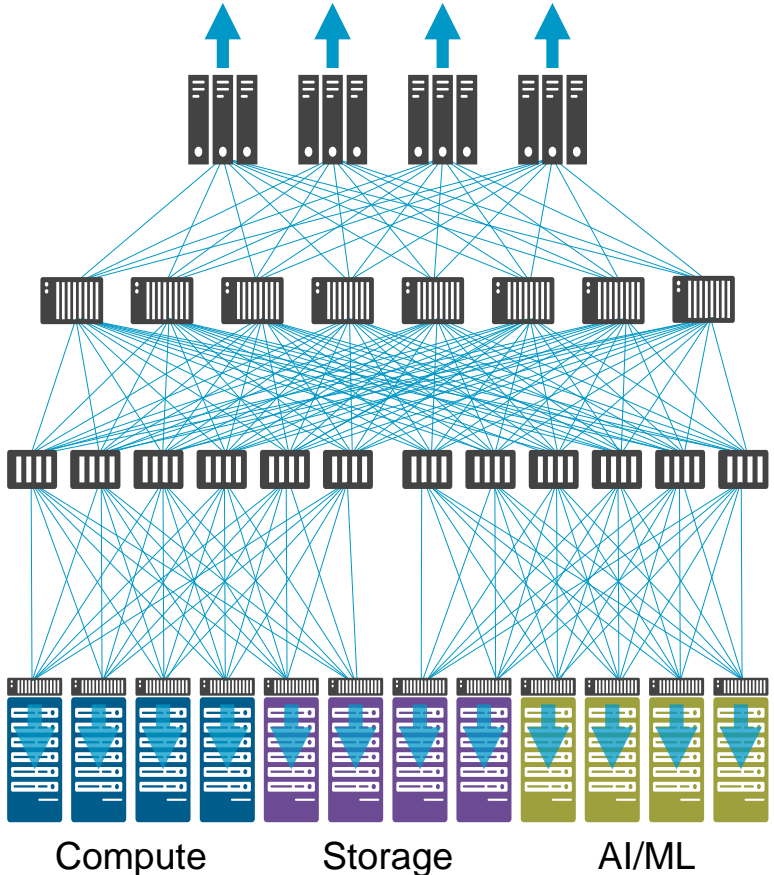
TH5 51.2T Bailly CPO (Co-Packaged Optics)

Optical Systems Division

March 2023

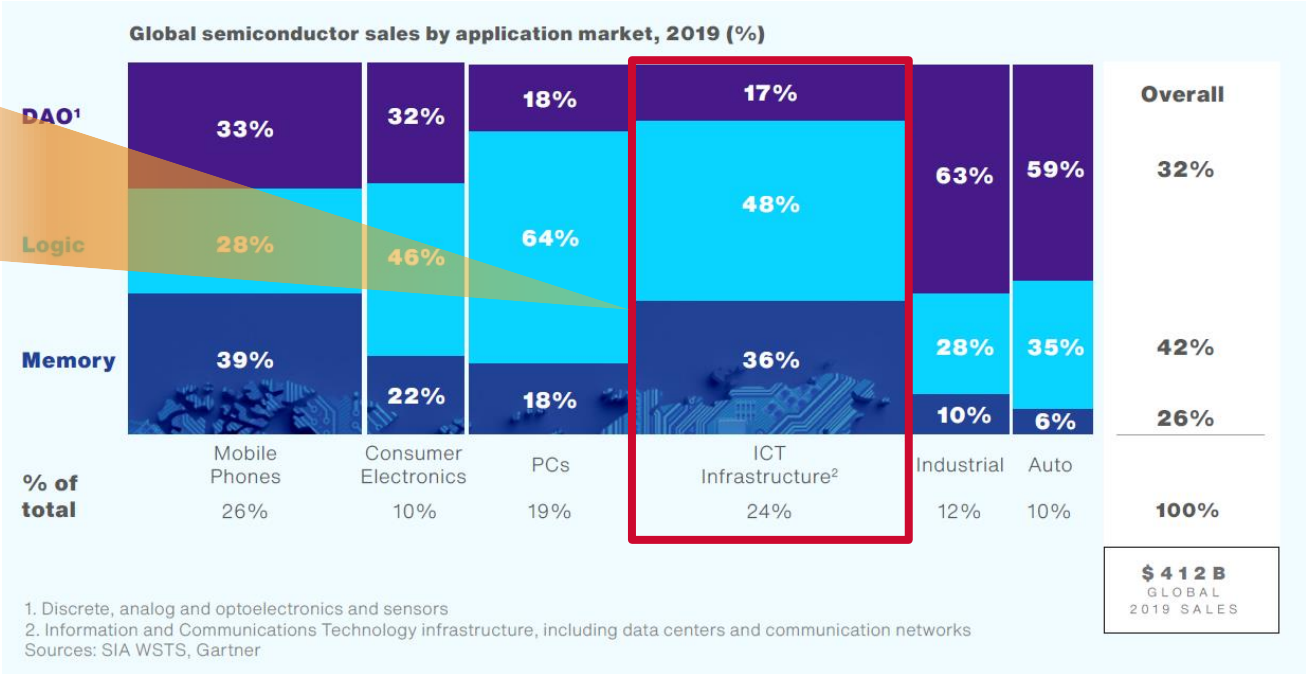


Compute Systems Trends Require More Data Movement



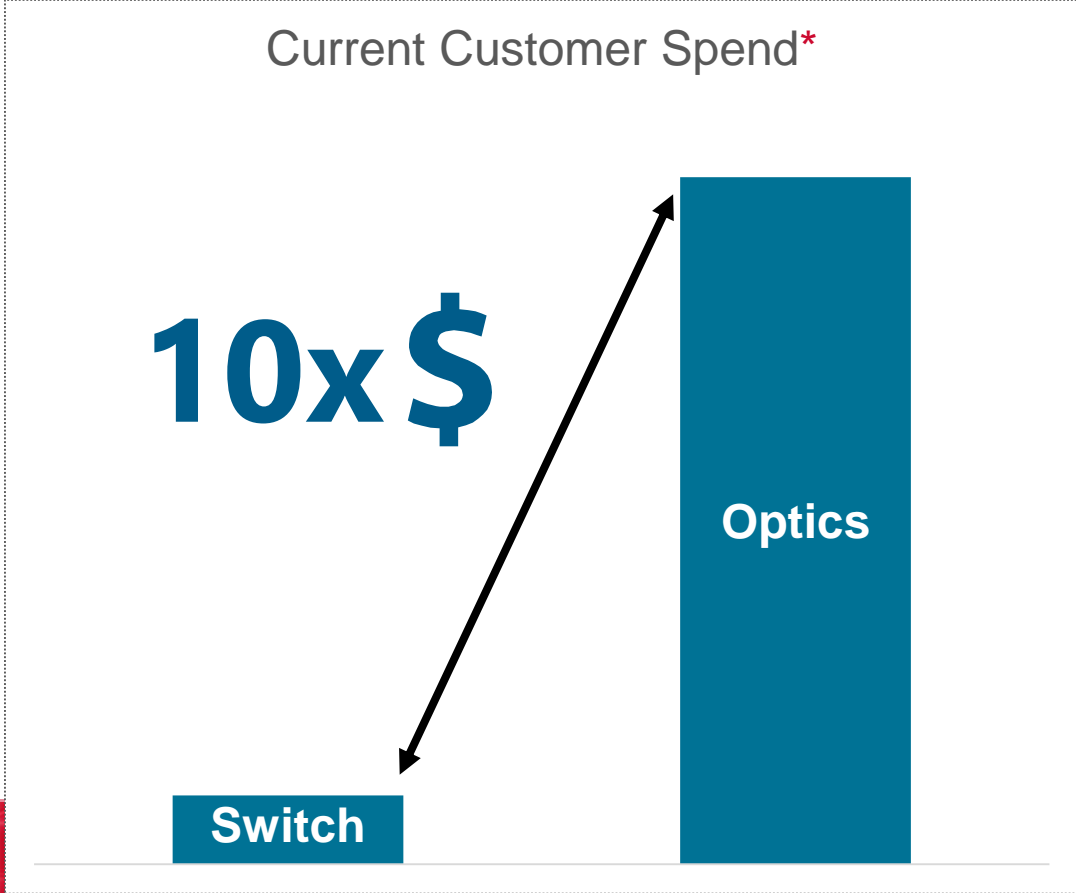
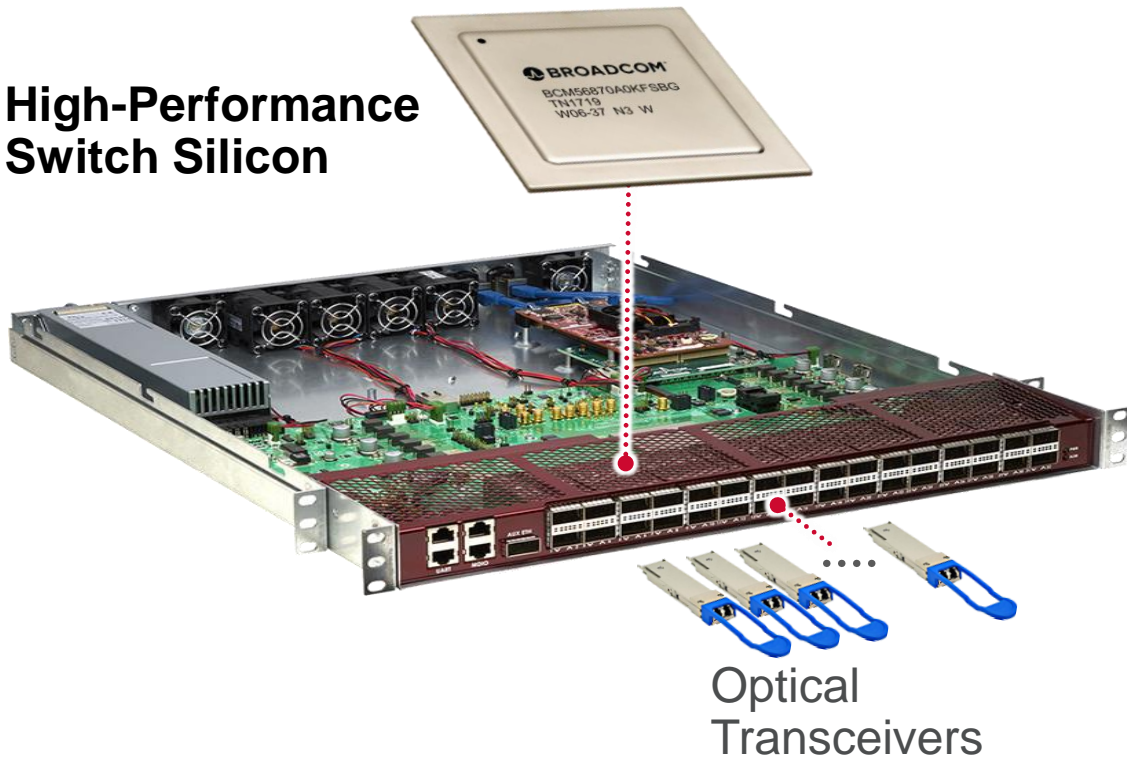
Clustering: Scale-out

Bandwidth Increase at Rack Level: Scale-up



Source: SIA/BCG Report: Strengthening the Global Semiconductor Supply Chain in an Uncertain Era, April 2021

Optical Interconnect Dominates Fabric Silicon Spend



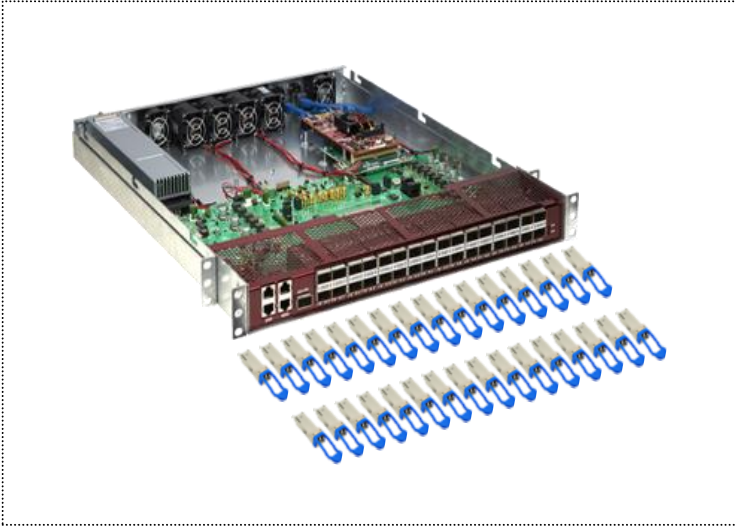
Opportunity for Step Function Improvement in Optical Connectivity

* Source: LightCounting, Dell'Oro, 650 Group and Broadcom internal estimates

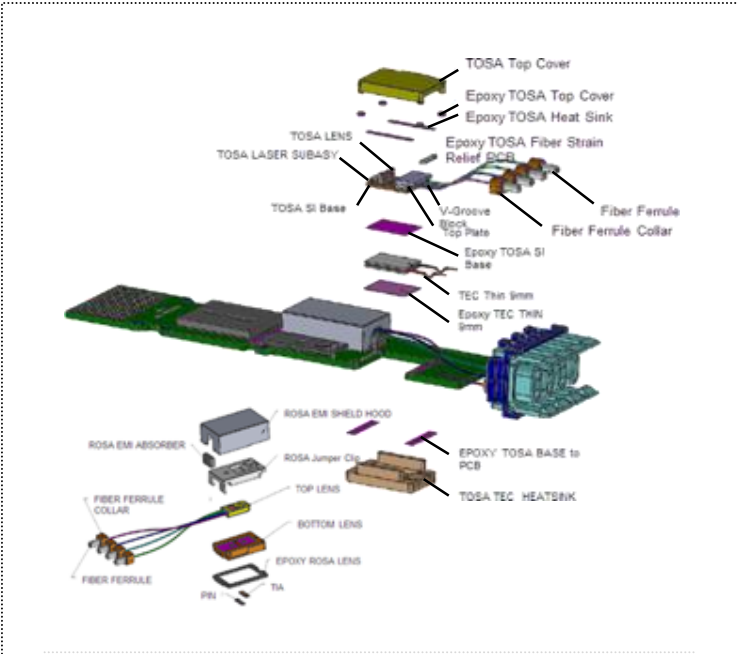


Current Market Solution for Network Connectivity: Pluggables

Current Networking Switch with Optical Modules

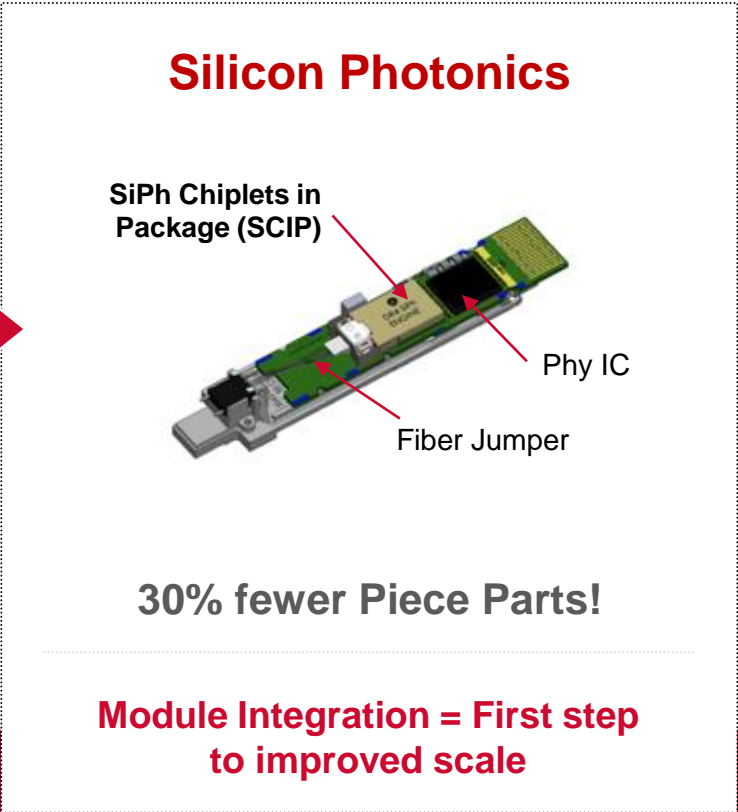


Conventional Module Design



Engineering and manufacturing limits to scale

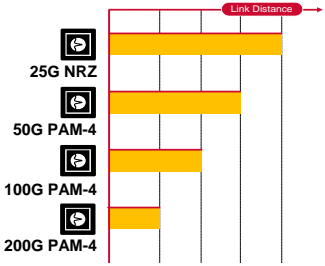
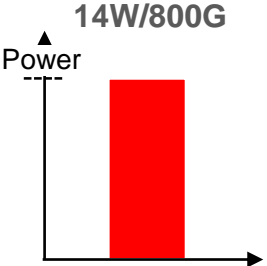
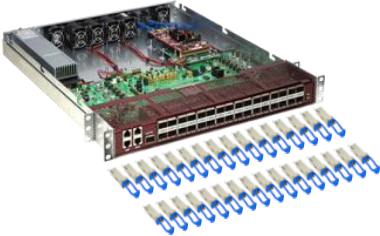
Integrated SiPh Module Design



Module solutions are still limited by face plate density, MFG costs, and power constraints

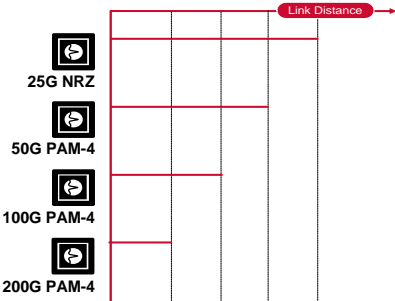
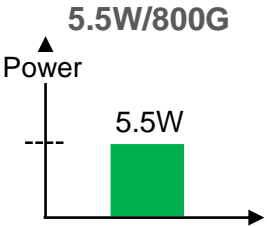
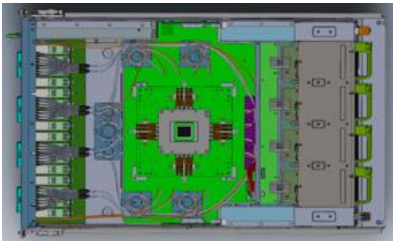
Co-Packaged Optics vs. Pluggables

Current Pluggables



Reach decreases with increasing rate
Power does not scale

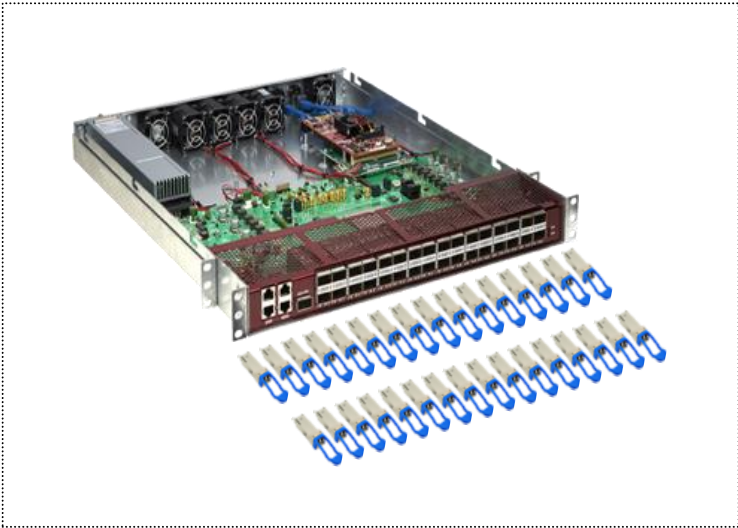
Co-Packaged Optics



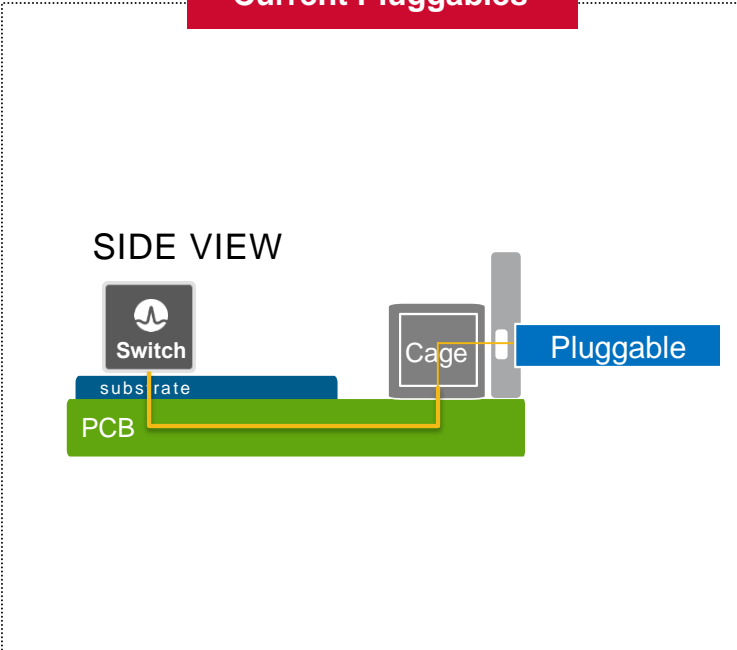
The solution for next generation interconnects

CPO provides Lower Power, Architecture Scaling to 200G/lane, 50% less components

Current Market Solution for Network Connectivity: Pluggables

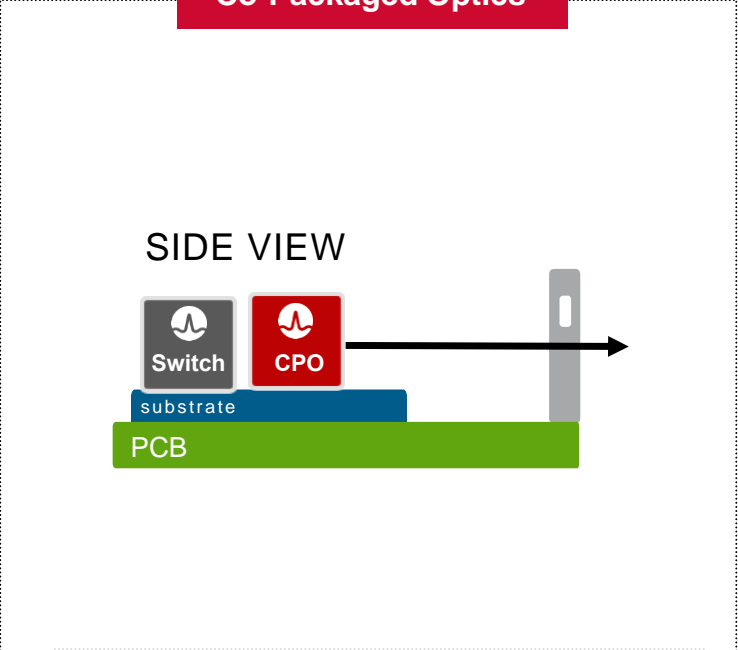


Current Pluggables



High power required to equalize signal through PCB and multiple connector discontinuities

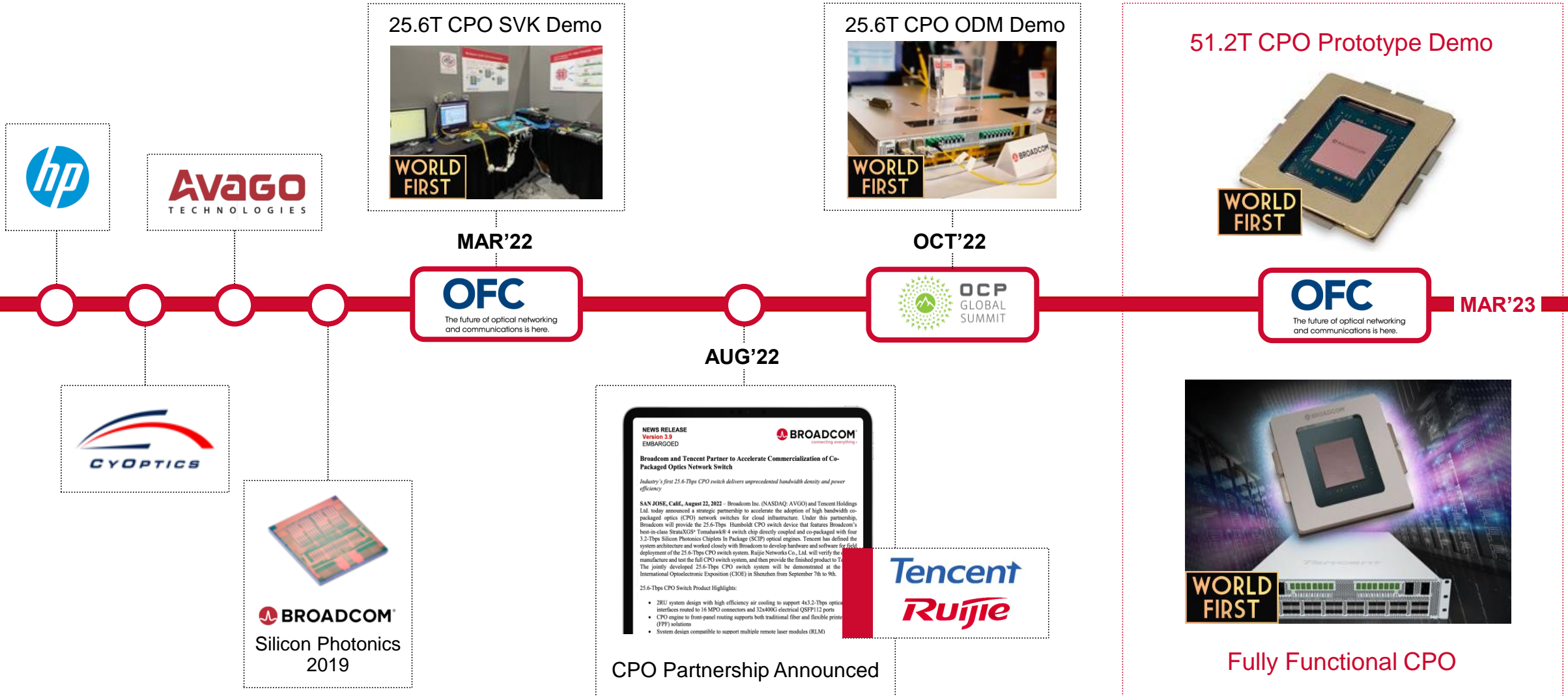
Co-Packaged Optics



CPO platform drives optics directly from Switch and reduces cost and power per bit.


CPO Provides the path to the lowest cost/bit and scalability to 200G/lane

Broadcom's CPO Timeline...



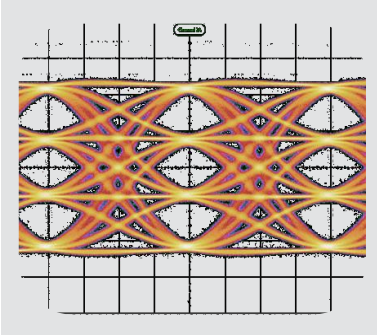
Broadcom's Disruptive Silicon + Photonics Platform ...

-  Highest Density Photonic Integrated Circuits
-  Advanced Semiconductor Packaging
-  Fiber Connectivity
-  Best-in-Class SerDes

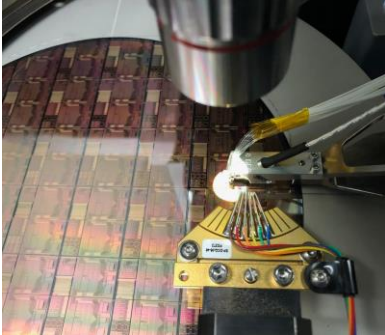


BROADCOM
Tomahawk5

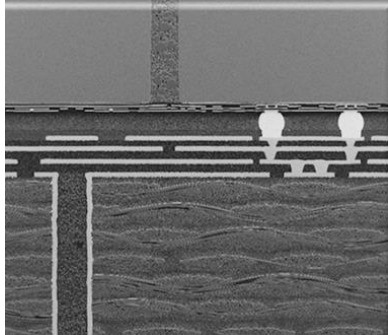
Switch Silicon



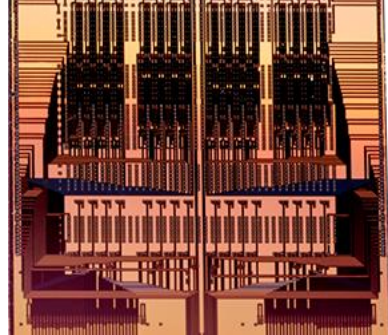
Mixed Signal IC



Optical Devices & Fabs



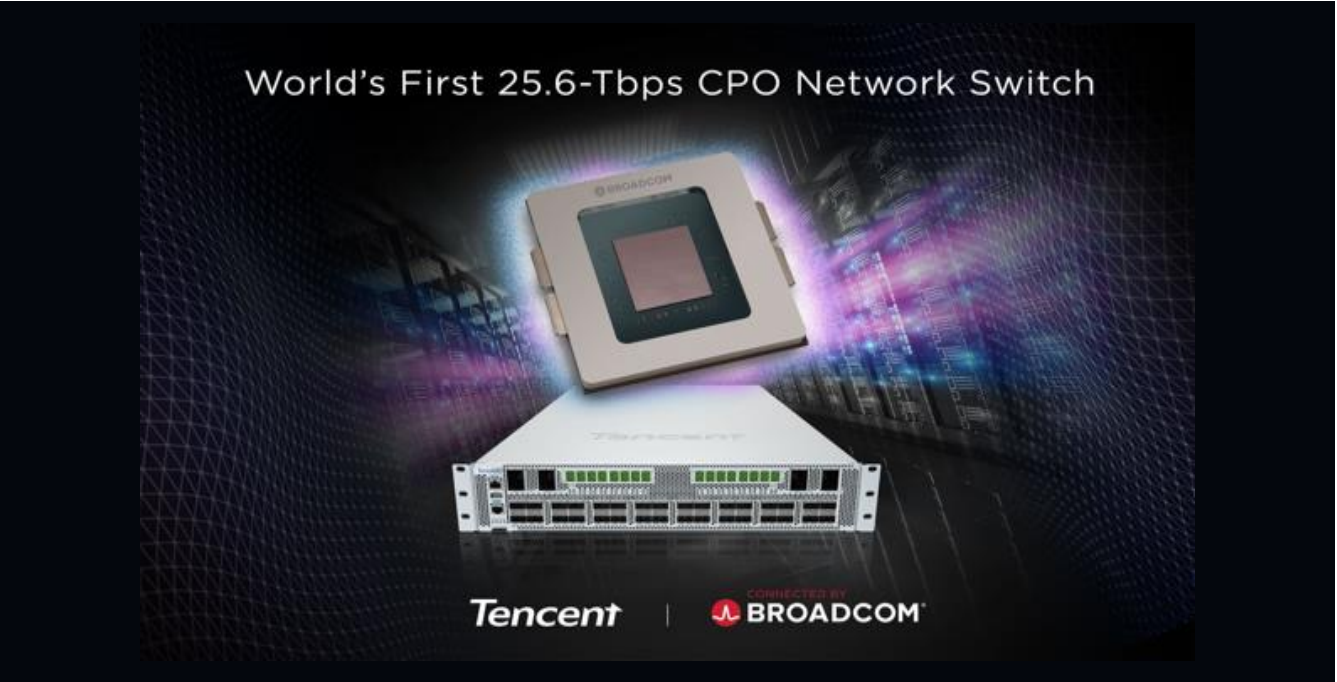
Advanced Packaging & Test



Silicon Photonics

Industry-Leading Economics, Volume, Power Efficiency at Scale

Tomahawk 4 – Humboldt 25.6T CPO





The future of optical networking and communications is here.

2023 Performance Demonstration

Final 25.6T CPO qualification systems shipping to end-customer

- CPO boxes are fully compliant
- **Error free across all 128 lanes**

25.6T CPO Power	Units	Measured Result
TH4 Power	W	367
CPO Power (128 lanes)	W	102
Air Temp	C	24



Tomahawk 5 – Bailly 51.2T CPO

Bailly CPO



51.2T Switch **FR4**

8 Silicon Photonic Engines
@ 6.4T (64ch)

51.2T CPO links, no
electrical links

Optical Power: **5.5W/800G**

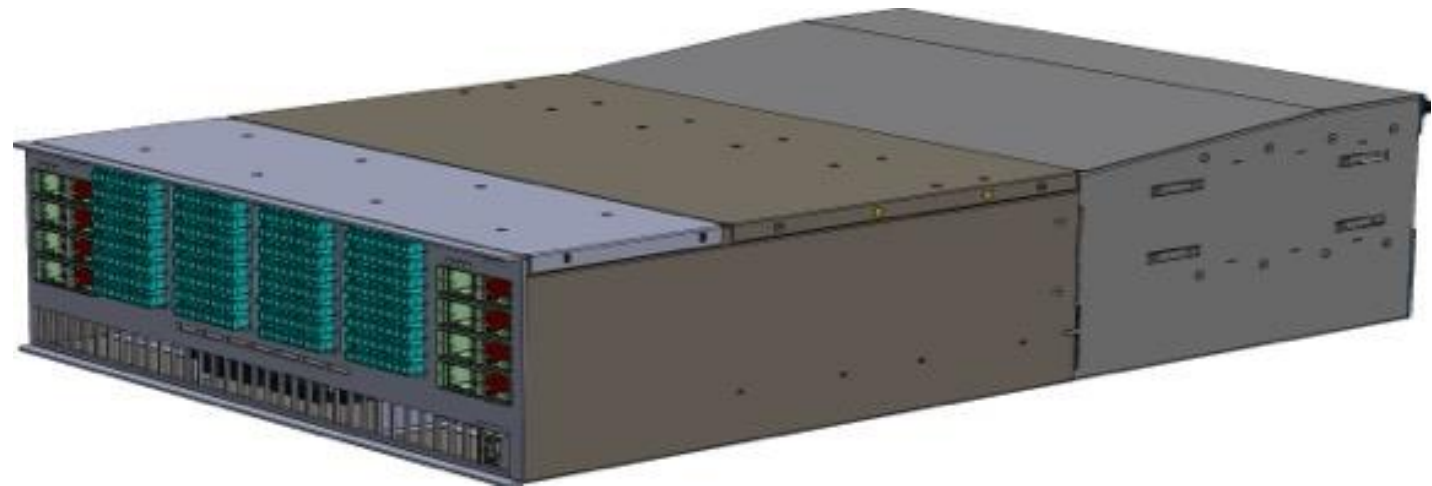
OFC

The future of optical networking
and communications is here.

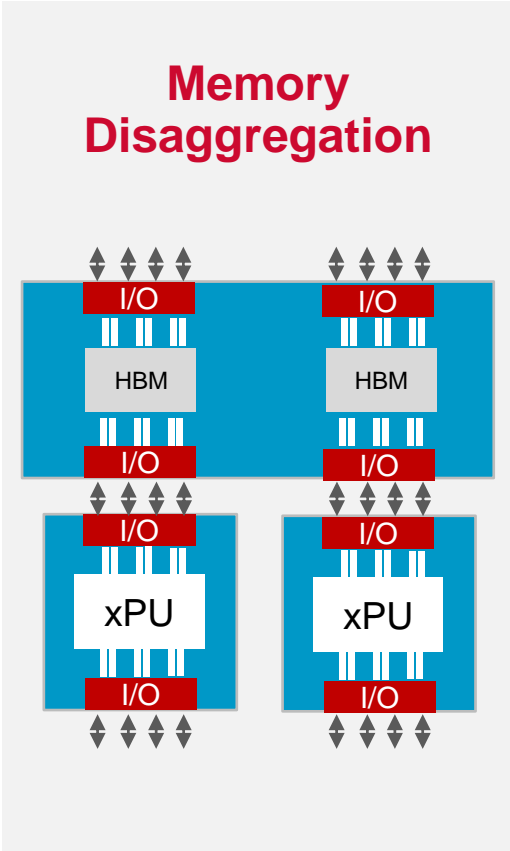
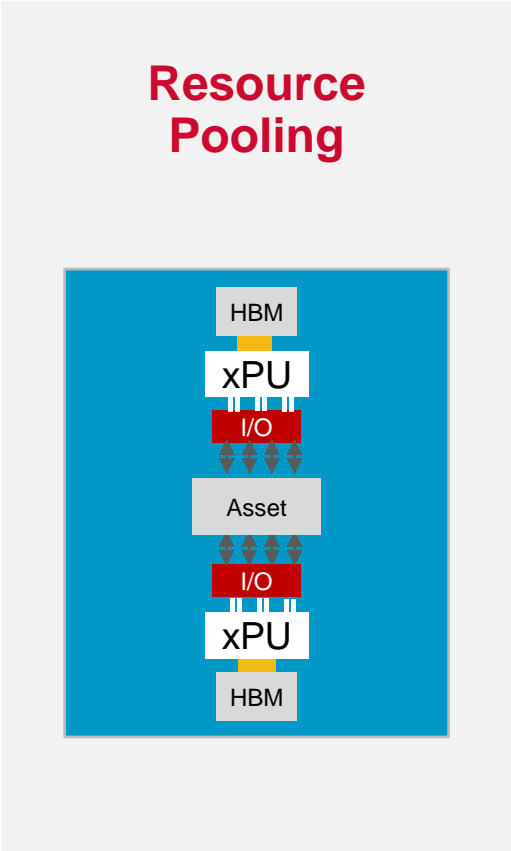
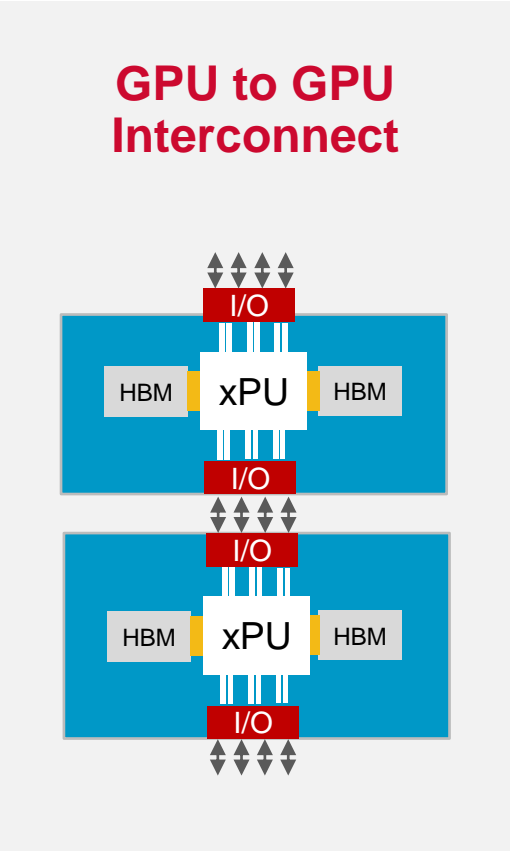
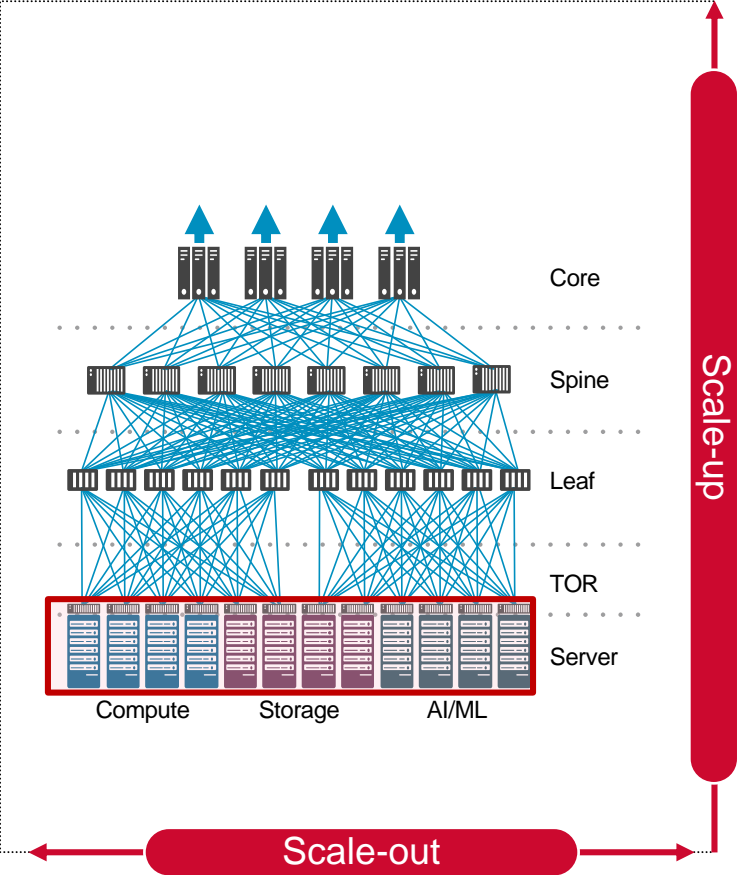
2023 Performance
Demonstration



30%
Power Savings



...will Launch the Industry's Explosive Adoption of the Integrated Optical Interconnect





BROADCOM[®]

connecting everything[®]